

2309413-1 ✓ ACTIVE

## DDR4 DIMM

TE Internal #: 2309413-1

Small Outline (SO), Stack Height 9.2 mm [.362 in], Right Angle

Module Orientation, 260 Position, DDR4 DIMM, SO DIMM Sockets

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[Connectors](#) > [Socket Connectors](#) > [Memory Sockets](#) > [SO DIMM Sockets](#) > [DDR4 SO DIMM Sockets](#)



DRAM Type: **Small Outline (SO)**

Stack Height: **9.2 mm [.362 in]**

Module Orientation: **Right Angle**

Number of Positions: **260**

Centerline (Pitch): **.5 mm, 7.3 mm [.02 in]**

[All DDR4 SO DIMM Sockets \(39\)](#)

## Features

### Product Type Features

Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Small Outline (SO)

### Configuration Features

Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	260

### Electrical Characteristics

DRAM Voltage	1.2 V
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### Signal Characteristics

SGRAM Voltage	1.2 V
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### Body Features

Ejector Location	Both Ends
Retention Post Material	Stainless Steel
Latch Material	High Temperature Thermoplastic



Retention Post Location	Both Ends
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Module Key Type	Offset Left
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Ejector Type	Locking
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Connector Profile	High
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#### Contact Features

Memory Socket Type	Memory Card
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Contact Underplating Material	Nickel
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PCB Contact Termination Area Plating Material	Gold Flash
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Contact Base Material	Copper Alloy
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Contact Current Rating (Max)	.5 A
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Contact Mating Area Plating Material	Gold Flash
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#### Termination Features

Insertion Style	Cam-In
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Termination Method to PCB	Surface Mount
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#### Mechanical Attachment

Mating Alignment Type	Standard Keying
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PCB Mount Retention	With
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PCB Mount Retention Type	Solder Peg
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Connector Mounting Type	Board Mount
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#### Housing Features

Housing Material	High Temperature Thermoplastic
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Housing Color	Black
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Centerline (Pitch)	.5 mm, 7.3 mm[.02 in]
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#### Dimensions

Stack Height	9.2 mm[.362 in]
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Row-to-Row Spacing	8.2 mm[.322 in]
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#### Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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#### Operation/Application

Circuit Application	Power
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#### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	500
Packaging Method	Tape & Reel

### Product Compliance

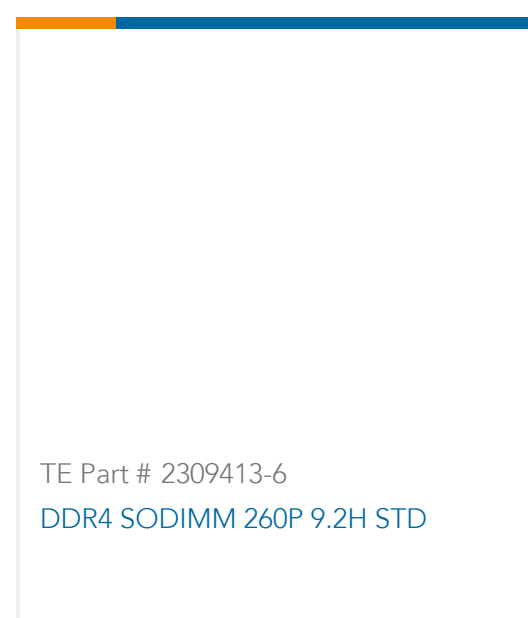
[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



## Also in the Series | DDR4 DIMM



DIMM Sockets(69)



SO DIMM Sockets(39)

## Customers Also Bought

TE Part #1-2199119-5  
M.2 ConnectorsTE Part #3-1879215-4  
CPF 0402 9K09 0.1% 25PPM 1K RLTE Part #2-2170808-3  
QSFP28, 1X2, CAGE ASSY, SPRING,  
HS, LPTE Part #2227249-2  
1x4 Cage Assy Bhd Bzl QSFP28TE Part #T1500103000-000  
H10B-AG-LBTE Part #753786-1  
DAHT 187 POS LOCK 18-14 ASSY

## Documents

### Product Drawings

[DDR4 SODIMM 260P 9.2H STD](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2309413-1\\_1.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309413-1\\_1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309413-1\\_1.3d\\_stp.zip](#)



English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

[Product Specifications](#)

[Application Specification](#)

English